



## Material Content Data Sheet



Sales Product Name	TLE7234SE			Issued		28. August 2013		
MA#	MA000931852							
Package	PG-DSO-20-56			Weight*		588.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.437	1.26	1.26	12631	12631
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		81	
	non noble metal	zinc	7440-66-6	0.190	0.03		322	
	non noble metal	iron	7439-89-6	3.797	0.64		6449	
	non noble metal	copper	7440-50-8	154.185	26.19	26.87	261853	268705
wire	noble metal	gold	7440-57-5	0.953	0.16	0.16	1619	1619
encapsulation	organic material	carbon black	1333-86-4	0.828	0.14		1407	
	plastics	epoxy resin	-	38.105	6.47		64715	
	inorganic material	silicondioxide	60676-86-0	375.256	63.73	70.34	637298	703420
leadfinish	non noble metal	tin	7440-31-5	4.487	0.76	0.76	7620	7620
plating	noble metal	silver	7440-22-4	0.800	0.14	0.14	1358	1358
glue	plastics	epoxy resin	-	0.684	0.12		1162	
	noble metal	silver	7440-22-4	2.052	0.35	0.47	3485	4647
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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